

Special Issue on Printed Electronics

Call for Papers

Printed electronics are changing our lives, which promise novel low-cost manufacturing technologies for display, renewable energy, and so forth and are rapidly advancing from laboratory inventions to commercial products. Printed electronics enable a variety of innovative products made from low-cost plastic thin film and represent multibillion dollars market, such as (i) electronic papers and books and flexible laptops; (ii) disposable personal electronics, such as cellular phones, iPods, and games; (iii) flexible exit sign and display “stickers”; (iv) electronic intelligent clothing that adjusts temperature, moisture, and color/fluorescence for best comfort and/or warning/protection; (v) flexible light weight solar cells that are put on clothing, and tents for military and medical applications. The recent research and development of novel materials, such as organic and polymeric semiconductors, carbon nanotubes, nanowires, quantum dots, and grapheme, are leading quantum jumps in printed electronics. This special issue intends to cover the most recent progress in printed electronics and the specific topics include:

- Printing technologies
- Functional materials for printed electronics and optoelectronics: conductive materials, organic and polymeric materials, ceramics, nanomaterials (CNT, nanowire, QDs, graphene, etc.)
- Smart substrates for printed electronics: flexible, stretchable, transparent
- Electrodes
- Transistors and logic
- RFID
- Light emitting diode for solid state lighting and display
- Electrochromic display and LCD display
- Photovoltaics
- Photodetector and sensor arrays
- Actuators
- Biosensor arrays

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